

Overview

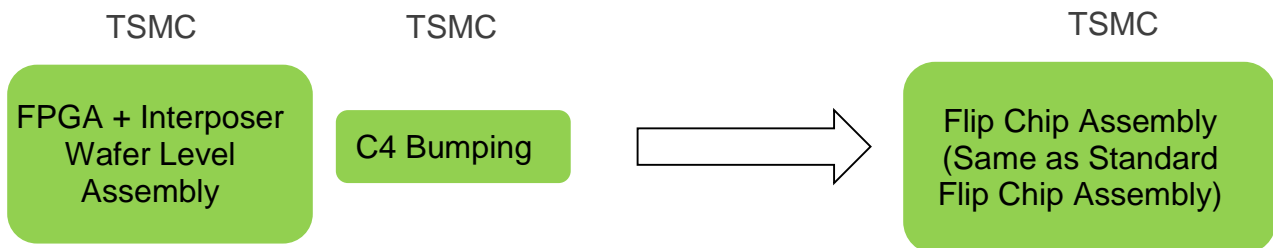
The purpose of this notification is to announce second source supplier qualification for substrate level assembly for SSIT (Stacked Silicon Interconnect Technology) products. There is no change in form, fit, function or reliability.

Description

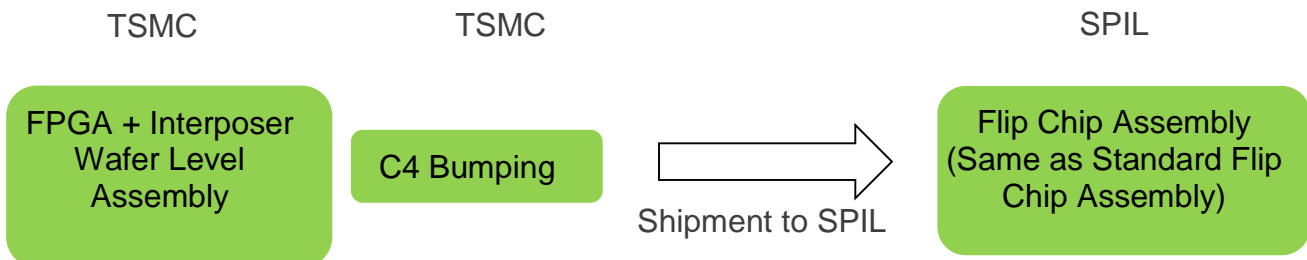
Xilinx qualified SPIL (Siliconware Precision Industries) as a second source supplier for substrate level assembly of stacked die wafers assembled at TSMC. SPIL has been Xilinx's qualified primary flip chip assembly supplier for over 16 years.

In this process flow, TSMC will complete the active die assembly on an interposer and will ship the stacked wafer to SPIL after C4 bumping. SPIL will assemble the stacked die wafer onto substrate similar to a standard flip chip assembly. There is no change in any material sets and the same packaging materials will be used for both process flows. This change is to ensure SSIT product supply continuity.

Current Process



Second Source Process



Products Affected

This change affects all speed, package, and temperature variations of “XC” commercial (C) and industrial (I) products reflected in [Table 1](#) and [Table 2](#). Any associated specification control document (SCD) versions of the standard part numbers are also affected.

Table 1: Virtex®-7 FPGA Products Affected

Device	Package-Pin	Device	Package-Pin
XC7VH870T	FLG1932	XC7VX1140T	FLG1926
XC7VH580T	FLG1155		FLG1928
	FLG1931		FLG1930
XC7V2000T	FHG1761		FL1926
	FLG1925		FL1928
	FH1761		
	FL1925		

Table 2: UltraScale™ FPGA Products Affected

Device	Package-Pin	Device	Package-Pin
XCVU440	FLGA2892	XCVU125	FLVA2104
	FLGB2377		FLVB1760
XCKU085	FLVA1517		FLVB2104
	FLVB1760		FLVC2104
	FLVF1924		FLVD1517
XCKU115	FLVA1517	XCVU160	FLGB2104
	FLVA2104		FLGC2104
	FLVB1760	XCVU190	FLGA2577
	FLVB2104		FLGB2104
	FLVD1517		FLGC2104
	FLVD1924		
FLVF1924			

Key Dates and Ordering Information

Xilinx will start cross-shipping from both assembly sites starting July 1, 2017.

Qualification Data

Xilinx qualification data for Virtex-7 (28nm) and UltraScale (20nm) production parts will be available upon request. UltraScale+ (16nm) products will start shipping from both assembly locations after production release.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
4/3/2017	1.0	Initial release.

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